



## An Exceptional Line Of **Depaneling Systems**

The WAND Depaneling System, a Larsen Manufacturing Business Unit, designs and builds today's most elite depaneling equipment for the Printed Circuit Board (PCB) industry. By greatly reducing and eliminating any stress or flex during the separation process of multiple populated Printed Circuit Boards (PCB's), the WAND Depaneling System safeguards against fractured joints, excess burrs, and leaves disjointed arrays quickly and cleanly separated. The WAND System is perfectly suited to accommodate medium to high volume PCB separation needs.

## The Singulation Process

The standard WAND Depaneling Singulation press is capable of punching individual or multiple populated panels within any specified working area. The operation is semi-automatic. Once the operator places the populated array into the "Depaneler", a shuttle transports the tool into the enclosed cutting area for the separation. The bottom tool returns to the operator, with the PCB board quickly and cleanly separated, and the cycle is complete.

**Total cycle time = 12.0**

### FEATURES:

- Air/Oil Power Pack
- Quick Change Clamping
- Die Package Storage Elevator (Optional)
- Air Logic Control
- 12 second cycle time
- Fully Enclosed Structure
- 1 1/2" Maximum Component Height including board thickness

### SAFETY:

- Optical Touch Controls
- Completely Guarded Cutting area
- Two Anti-Repeat / Anti-Tie Down Finger Controlled Start Mechanisms
- Built In Safety Light Curtains
- Package position sensors prevent power pack from cycling if package is out of position
- (4) Pneumatic Clamps Lock upper Package in Position

